

UNCONTROLLED DOCUMENT

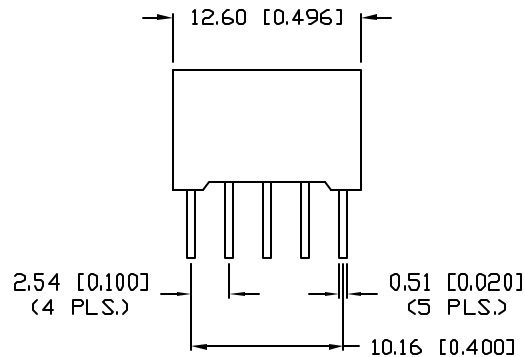
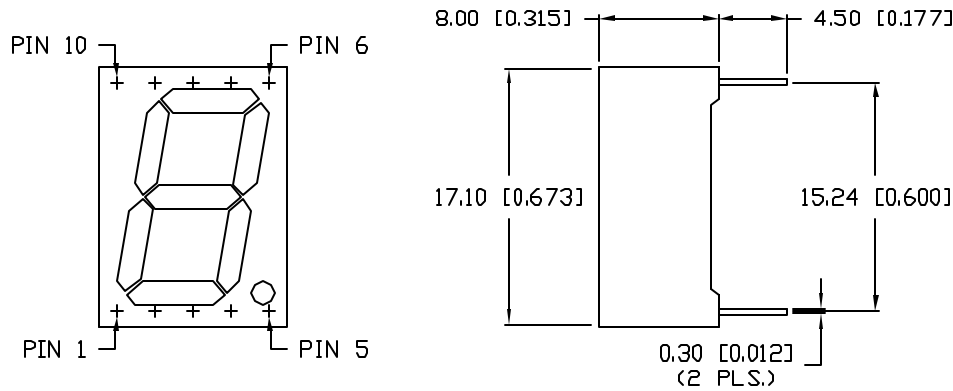
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PART NUMBER

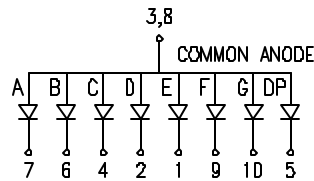
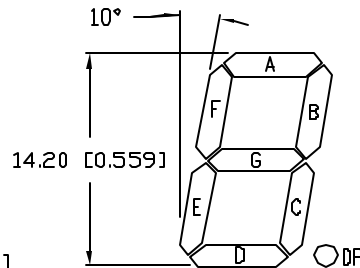
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PRELIMINARY IN P/N DIR



DIGIT DETAIL



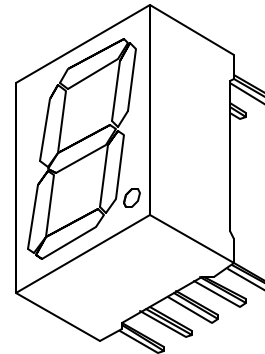
ELECTRO-OPTICAL CHARACTERISTICS  $T_A=25^\circ\text{C}$   $I_f=10\text{mA}$

PARAMETER	MIN	TYP	MAX	UNITS	TEST COND
PEAK WAVELENGTH		574		nm	
FORWARD VOLTAGE		2.2	2.6	$V_f$	
REVERSE VOLTAGE	5.0			$V_r$	$I_r=100\mu\text{A}$
AXIAL INTENSITY		7000		$\mu\text{cd}$	$I_f=10\text{mA}$
EMITTED COLOR:	GREEN				
FACE COLOR:	GRAY				
SEGMENT COLOR:	MILKY WHITE DIFFUSED				

LIMITS OF SAFE OPERATION AT  $25^\circ\text{C}$  PER CHIP

PARAMETER	MAX	UNITS
PEAK FORWARD CURRENT*	150	mA
STEADY CURRENT	25	mA
POWER DISSIPATION	105	mW
DERATE FROM $25^\circ\text{C}$	-1.2	mW/ $^\circ\text{C}$
OPERATING, STORAGE TEMP.	-40 TO +85	$^\circ\text{C}$
SOLDERING TEMP.	+260	$^\circ\text{C}$
2.0mm FROM BODY		3 SEC. MAX

\*  $t < 10\mu\text{s}$



\*UNLESS OTHERWISE SPECIFIED TOLERANCES PER DECIMAL PRECISION ARE: X= $\pm 1$  ( $\pm 0.039$ ), XX= $\pm 0.5$  ( $\pm 0.020$ ), XXX= $\pm 0.25$  ( $\pm 0.010$ ), XXXX= $\pm 0.127$  ( $\pm 0.005$ ). LEAD SIZE= $\pm 0.05$  ( $\pm 0.002$ ), LEAD LENGTH= $\pm 0.75$  ( $\pm 0.030$ ), MIN= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$  DECIMAL PRECISION, MAX= $\begin{matrix} +0.00 \\ -0.00 \end{matrix}$  DECIMAL PRECISION

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0.56" SEVEN SEGMENT, SINGLE DIGIT DISPLAY,  
574nm GREEN CHIPS, GRAY FACE WITH WHITE SEGMENTS,  
COMMON ANODE.

**RELIABILITY NOTE**  
OUR MANY YEARS OF EXPERIENCE DATA ACCUMULATION INDICATE THAT SOLDER HEAT IS A MAJOR CAUSE OF EARLY AND FUTURE FAILURE. PLEASE PAY ATTENTION TO YOUR SOLDERING PROCESS.

DRAWN BY:

CHECKED BY:

APPROVED BY:

DATE: 6.19.03

BC

PAGE: 1 OF 1

SCALE: N/A